Product Change Notification

Change Notification #:	**116245 - 00**
Change Title:	**Select Intel® SSD Pro 7600p Series Intel® SSD 760p Series Intel® SSD E 6100p Series, PCN 116245-00, Product Material, Add Alternate Component**
Date of Publication:	**May 16, 2018**

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	June 1, 2018

Description of Change to the Customer:

The Intel® SSD Pro 7600p Series SKUs listed in the products affected table below will have the following change.

- An alternate vendor (Winbond) for the LPDDR3 will be added to the bill of materials to insure adequate supply for production.

Customer Impact of Change and Recommended Action:

Intel anticipates no functional impact to customers since the parts are interchangeable but encourages customer to understand the changes and determine the impact to their operations if any.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Name	Product Code	MM#
Intel® SSD 760p Series (128GB, M.2 80mm PCIe 3.0 x4, 3D2, TLC) Retail Box 10 Pack	SSDPEKKW128G8XT	963289
Intel® SSD 760p Series (256GB, M.2 80mm PCIe 3.0 x4, 3D2, TLC) Retail Box 10 Pack	SSDPEKKW256G8XT	963290
Intel® SSD Pro 7600p Series (128GB, M.2 80mm PCIe 3.0 x4, 3D2, TLC) Retail Box Single Pack	SSDPEKKF128G8X1	963303
Intel® SSD Pro 7600p Series (256GB, M.2 80mm PCIe 3.0 x4, 3D2, TLC) Retail Box Single Pack	SSDPEKKF256G8X1	963304
Intel® SSD E 6100p Series (128GB, M.2 80mm PCIe 3.0 x4, 3D2, TLC) Generic Single Pack	SSDPEKKR128G801	963756
Intel® SSD E 6100p Series (256GB, M.2 80mm PCIe 3.0 x4, 3D2, TLC) Generic Single Pack	SSDPEKKR256G801	963758
Intel® SSD E 6100p Series (128GB, M.2 80mm PCIe 3.0 x4, 3D2, TLC) Generic 10 Pack	SSDPEKKR128G810	963759
Intel® SSD E 6100p Series (256GB, M.2 80mm PCIe 3.0 x4, 3D2, TLC) Generic 10 Pack	SSDPEKKR256G810	963760
Intel® SSD 760p Series (128GB, M.2 80mm, PCIe 3.0 x4, 3D2, TLC) Generic Single Pack	SSDPEKKW128G801	963928
Intel® SSD 760p Series (256GB, M.2 80mm, PCIe 3.0 x4, 3D2, TLC) Generic Single Pack	SSDPEKKW256G801	963929

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
May 16, 2018	00	Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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